



Intel-Based Platforms

Intel® Xeon® Processor E3-1200, E5-2600,
E5-2600 v2, E5-2400 v2 Product Families and
Intel® Core® i3/i5/i7 Processors Based Platforms



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Intel® Xeon Phi™ Coprocessor

Power your breakthrough innovations with the highly parallel processing of the Intel® Xeon Phi™ coprocessor. Now you can think “reuse” rather than “recode” with x86 compatibility. Languages, tools, and applications run smoothly across the full spectrum of Intel® Xeon® family-based platforms. Plus, discover the flexibility of a coprocessor that can also host an OS.

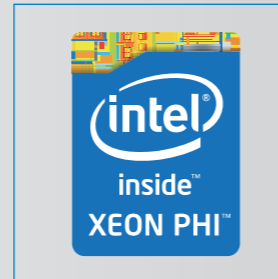
- Large numbers of cores and threads enable efficient execution of hundreds of simultaneous tasks to dramatically boost aggregate performance for highly-parallel applications.
- Enables broad reuse of existing code. Also allows developers to use familiar tools and methods and to maintain a common code base for Intel® Xeon® processors and Intel® Xeon Phi™ coprocessors.
- Can operate as a dependent coprocessor or an independent server node to enable flexible usage models and optimized support for diverse hardware and software environments.
- Supports standard clustering models for simple integration into clustered environments.
- Provides exceptional compute density and energy efficiency.
- Enables simple scaling of highly-parallel execution resources to deliver desired performance levels.

Target Markets and Applications

Life Sciences, Energy, 3D Design, Research and Weather.

The Intel® Xeon Phi™ Coprocessor 5110P®

The Intel® Xeon Phi™ coprocessor 5110P, based on Intel® Many Integrated Core (MIC) architecture, complements the industry leading performance and energy-efficiency of the Intel® Xeon® processor E5 family to enable dramatic performance gains for some of today's most demanding applications. You can now achieve optimized performance for even your most highly-parallel technical computing workloads, while maintaining a unified hardware and software environment.



1. Software and workloads used in performance tests may have been optimized for performance only on Intel microprocessors. Performance tests, such as SYSmark and MobileMark, are measured using specific computer systems, components, software, operations and functions. Any change to any of those factors may cause the results to vary. You should consult other information and performance tests to assist you in fully evaluating.
2. Claim based on calculated theoretical peak double precision performance capability for a single coprocessor: 16 DP flops/clock/core * 60 cores * 1.053 GHz = 1.01088 Tflops.
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Intel® Xeon® processor E5-2600 Product Family

The Intel® Xeon® processor E5 family supports key cloud requirements that make your data center agile and more responsive to changing business needs. Maintaining industry leadership for power efficiency and continuing Intel® Xeon® processor performance advancements, the Intel® Xeon® processor E5 family gives you additional performance when you need it for single- and multi-threaded applications, including increased floating-point performance for technical computing workloads.

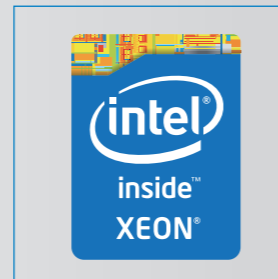
- Faster Performance for Peak Workloads
- Up to 2X Performance Gains
- Eliminating Network Bottlenecks
- Strengthening Security in the Enterprise and the Cloud
- Driving down Energy Cost at Every Level
- Optimized Platform Solutions

Target Markets and Applications

Virtualization, Storage, HPC, Datacenter, IPDC and Public-Private Cloud Computing.

Intel® Xeon® processor E5-2600 Product Family

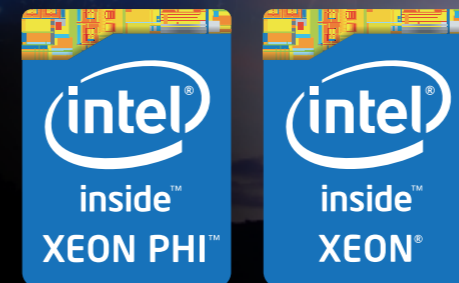
Servers, workstations, and storage solutions based on the new Intel® Xeon® processor E5-2600 Product family deliver the best combination of performance, built-in capabilities, and cost-effectiveness to make data centers more flexible and efficient. From virtualization and cloud computing solutions to design automation or real-time financial transactions, you'll be delighted by better than ever performance no matter what tasks you face.



1. Available on select Intel® Core™ processors. Requires an Intel® HT Technology-enabled system. Consult your PC manufacturer. Performance will vary depending on the specific hardware and software used. For more information including details on which processors support HT Technology, visit <http://www.intel.com/info/hyperthreading>.
2. Requires a system with Intel® Turbo Boost Technology. Intel Turbo Boost Technology and Intel Turbo Boost Technology 2.0 are only available on select Intel® processors. Consult your PC manufacturer. Performance varies depending on hardware, software and system configuration. For more information, visit www.intel.com/go/turbo/.
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INTEL-BASED HPC/GPU PLATFORMS



<HPC> TYAN offers multiple High Performance Computing (HPC) server platforms that support either the newest Intel® Xeon® processor E5-2600/ E52600 v2 product family or Intel® Xeon® 5600 series processor . Both platforms are designed for high performance in massively parallel computing environments which meet users' complex workloads requirements while accelerating general computing capability. Ranging from mainstream workloads to the most challenging computing applications, TYAN offers various platforms that support our customers need to build scalable, efficient, flexible, and easily managed datacenters as well as other complicated high performance computing infrastructure.

<GPU> Supporting the latest Intel® Xeon® Processor E5-2600/ E52600 v2 product families, Intel® Xeon® 5600 Series Processor and Graphic Computing Processors (GPU), TYAN's GPU platforms offer data accuracy and double precision floating-point performance with uncompromised accuracy. TYAN's Intel Xeon based GPU platforms range from 1 GPU up to 8 GPUs inside traditional 1U, 2U and 4U rackmount chassis, which help reduce the rack space requirements required for high performance applications. With the right workload, these platforms can offer higher performance and reduce power consumption when compared to traditional CPU centric platforms.

Target Applications:

- Bio-Informatics, Life Sciences and Computational Chemistry
- Electronic-Design Automation
- Computational Finance and Computational Fluid Dynamics
- Computer Vision and MATLAB Acceleration
- Data mining, Analytics and Databases
- Imaging, Molecular Dynamics, Weather, Climate Modeling and Atmospheric
- Oil, Gas and Petroleum Exploration
- Physics and Scientific Research

FT77A-B7059-LE

B7059F77AV4R-LE(BTO)



Intel® Xeon Phi™ 3120A Starter Kit + TYAN FT77A-B7059-LE



80 PLUS PLATINUM 4U High-density GPU Server Platform for GPGPU applications

Model Number	FT77A-B7059-LE		
Enclosure Form Factor	4U (30.31" in depth)		
Supported CPU	(1) Intel® Xeon® E5-2600 v2 Series (Ivy Bridge-EP)		
Chipset	Intel® C602 PCH + (2) PLX PEX8747		
Chipset Interconnection	Intel® QPI 8.0/ 7.2/ 6.4GT/s		
Number of DIMM Slot	12		
Memory Type (max. capacity)	LR-DDR3 1866/1600/1333/ 1066 w/ ECC (768GB) R-DDR3 1866/1600/1333/ 1066 w/ ECC (384GB) U-DDR3 1866/1600/1333/ 1066 w/ ECC (192GB)		
Storage Controller	Intel® C602 PCH (SATA 6Gb/s & 3Gb/s)		
RAID Support	RAID 0, 1, 5, 10 (Intel® RSTe 3.0)		
Networking	(2) GbE (shared IPMI NIC)		
PCI Expansion Slots	(1) PCI-E x8 (Gen.3) slot + (4) PCI-E (Gen.3) x16 slots (3) PCI-E (Gen.2) slots + (1) PCI 32bit slot		
Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B7059F77AV4R-LE(BTO)	(4) Internal 3.5"	N/A	(1+1) 1,000W/1,200W RPSU

FT68-B7910

B7910F68W32HR-2T / B7910F68W64HR-2T



80 PLUS PLATINUM 4U4S High Performance Server/Storage Platform

Model Number	FT68-B7910		
Enclosure Form Factor	4U (26.77" in depth)		
Supported CPU	(4) Intel® Xeon® E5-4600 v2 Series (Ivy Bridge-EP 4S)		
Chipset	Intel® C602 PCH		
QuickPath Interconnect	Intel® QPI 8.0/ 7.2/ 6.4GT/s		
Number of DIMM Slot	32 / (8+8+8)		
Memory Type (max. capacity)	LR-DDR3 1866/1600/1333/ 1066 w/ ECC (1024GB) R-DDR3 1866/1600/1333/ 1066 w/ ECC (512GB) U-DDR3 1866/1600/1333/ 1066 w/ ECC (256GB)		
Storage Controller	(2) LSI SAS2308 (SAS 6Gb/s)		
RAID Support	RAID 0, 1, 1E, 10 (LSI Integrated RAID)		
Networking	(2)10GbE + (1) IPMI		
PCI Expansion Slots	(6) PCI-E (Gen.3) x16 + (2) PCI-E (Gen.3) x8		
Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B7910F68W32HR-2T	(32) hot-swap 2.5"	32-port SAS/ SATA 6Gb/s	(1+1) 1600W RPSU
B7910F68W64HR-2T	(64) hot-swap 2.5"	64-port SAS/ SATA 6Gb/s	(1+1) 1600W RPSU

FT77B-B7059

B7059F77BV10R (BTO) / B7059F77BV10R-2T (BTO)



80 PLUS PLATINUM 4U High-density GPU Server Platform for GPGPU applications

Model Number	FT77B-B7059		
Enclosure Form Factor	4U (30.31" in depth)		
Supported CPU	(2) Intel® Xeon® E5-2600 v2 Series (Ivy Bridge-EP)		
Chipset	Intel® C602 PCH + (4)PLX PEX8747		
Chipset Interconnection	Intel® QPI 8.0/ 7.2/ 6.4GT/s		
Number of DIMM Slot	24/ (12+12)		
Memory Type (max. capacity)	LR-DDR3 1866/1600/1333/ 1066 w/ ECC (768GB) R-DDR3 1866/1600/1333/ 1066 w/ ECC (384GB) U-DDR3 1866/1600/1333/ 1066 w/ ECC (192GB)		
Storage Controller	Intel® C602 PCH (SATA 6Gb/s & 3Gb/s)		
RAID Support	RAID 0, 1, 5, 10 (Intel® RSTe 3.0)		
Networking	(2) 10GbE/ GbE (shared IPMI NIC)		
PCI Expansion Slots	(8) PCI-E (Gen3) x16 slots + (2) PCI-E (Gen3) x8 slots(one for mezzanine card) (3) PCI-E (Gen2) x1 slots + (1) PCI 32-bit slot		
Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B7059F77BV10R (BTO)	(10) Internal 3.5"	N/A	(2+1) 3,200W RPSU
B7059F77BV10R-2T (BTO)	(10) Internal 3.5"	N/A	(2+1) 3,200W RPSU

GN70-B7056

B7056G70V8HR / B7056G70W8HR
B7056G70V8HR-2T (BTO)



80 PLUS GOLD 2U Rack-Optimized Server Platform for HPC

Model Number	GN70-B7056		
Enclosure Form Factor	2U (27.56" in depth)		
Supported CPU	(2) Intel® Xeon® E5-2600 v2 Series (Ivy Bridge-EP)		
Chipset	Intel® C602 PCH		
QuickPath Interconnect	Intel® QPI 8.0/ 7.2/ 6.4GT/s		
Number of DIMM Slot	16/ (8+8)		
Memory Type (max. capacity)	LR-DDR3 1866/1600/1333/ 1066 w/ ECC (512GB) R-DDR3 1866/1600/ 1333/ 1066 w/ ECC (256GB) U-DDR3 1866/1600/1333/ 1066 w/ ECC (128GB)		
Storage Controller	Intel® C602 PCH (SATA 6Gb/s & 3Gb/s) LSI SAS2308 (SAS 6Gb/s)		
RAID Support	RAID 0, 1, 5, 10 (Intel® RSTe 3.0) RAID 0, 1, 1E, 10 (LSI Integrated RAID)		
Networking	(2) 10GbE + (1) GbE (shared IPMI NIC) (-2T SKU) (3) GbE (shared IPMI NIC), or		
PCI Expansion Slots	(2) PCI-E (Gen.3) x16 + (2) PCI-E (Gen.3) x8		
Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B7056G70V8HR	(8) hot-swap 3.5"	8-port SAS/ SATA 6Gb/s	(1+1) 770W RPSU
B7056G70W8HR	(8) hot-swap 3.5"	8-port SAS/ SATA 6Gb/s	(1+1) 770W RPSU
B7056G70V8HR-2T (BTO)	(8) hot-swap 3.5"	8-port SAS/ SATA 6Gb/s	(1+1) 770W RPSU

HPC

YR190-B7058-X2

B7058Y190X2-045GV4H



80 PLUS GOLD **80 PLUS SILVER**
1U Rack-Optimized Server Platform for HPC

Model Number	YR190-B7058-X2		
Enclosure Form Factor	1U (28.74" in depth) / 2 Nodes		
Supported CPU (per node)	(2) Intel® Xeon® E5-2600 v2 Series (Ivy Bridge-EP)		
Chipset (per node)	Intel® C602 PCH		
QuickPath Interconnect (per node)	Intel® QPI 8.0/ 7.2/ 6.4GT/s		
Number of DIMM Slot (per node)	8/ (4+4)		
Memory Type (max. capacity) (per node)	LR-DDR3 1866/1600/1333/ 1066 w/ ECC (256GB) R-DDR3 1866/1600/ 1333/ 1066 w/ ECC (128GB) U-DDR3 1866/1600/1333/ 1066 w/ ECC (64GB)		
Storage Controller (per node)	Intel® C602 PCH (SATA 6Gb/s & 3Gb/s)		
RAID Support (per node)	RAID 0, 1, 5, 10 (Intel® RSTe 3.0)		
Networking (per node)	(2) GbE + (1) PHY dedicated IPMI		
PCI Expansion Slots (per node)	(1) PCI-E (Gen.3) x16		
Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B7058Y190X2-045GV4H	(4) hot-swap 2.5" (per node)	4-port SAS/ SATA 6Gb/s (per node)	(1) 450W PSU (per node)

TA77-B7061

B7061T77W8HR



80 PLUS PLATINUM
2U High-density GPU Server Platform for GPGPU applications



Model Number	TA77-B7061		
Enclosure Form Factor	2U (27.56" in depth)		
Supported CPU	(2) Intel® Xeon® E5-2600 v2 Series (Ivy Bridge-EP)		
Chipset	Intel® C602 PCH		
Chipset Interconnection	Intel® QPI 8.0/ 7.2/ 6.4GT/s		
Number of DIMM Slot	16/ (8+8)		
Memory Type (max. capacity)	LR-DDR3 1866/1600/1333/ 1066 w/ ECC (512GB) R-DDR3 1866/1600/1333/ 1066 w/ ECC (256GB) U-DDR3 1866/1600/1333/ 1066 w/ ECC (128GB)		
Storage Controller	LSI SAS2308 (SAS 6Gb/s)		
RAID Support	RAID 0, 1, 1E, 10 (LSI Integrated RAID)		
Networking	(2) GbE + (1) PHY dedicated IPMI		
PCI Expansion Slots	(4) PCI-E (Gen.3) x16 + (1) PCI-E (Gen.3) x8		
Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B7061T77W8HR	(8) hot-swap 2.5"	8-port SAS/ SATA 6Gb/s	(1+1) 1,600W RPSU
*B7061T77W8HR-NXXXX	(8) hot-swap 2.5"	8-port SAS/ SATA 6Gb/s	(1+1) 1,600W RPSU

GPGPU

FT48-B7055

B7055F48V8HR / B7055F48W8HR
 B7055F48V8HR-2T (BTO)



80 PLUS GOLD
4U High-density GPU Server Platform for GPGPU applications

Model Number	FT48-B7055		
Enclosure Form Factor	4U (27.56" in depth)		
Supported CPU	(2) Intel® Xeon® E5-2600 v2 Series (Ivy Bridge-EP)		
Chipset	Intel® C602 PCH		
Chipset Interconnection	Intel® QPI 8.0/ 7.2/ 6.4GT/s		
Number of DIMM Slot	8/ (4+4)		
Memory Type (max. capacity)	LR-DDR3 1866/1600/1333/ 1066 w/ ECC (768GB) R-DDR3 1866/1600/1333/ 1066 w/ ECC (384GB) U-DDR3 1866/1600/1333/ 1066 w/ ECC (192GB)		
Storage Controller	Intel® C602 PCH (SATA 6Gb/s & 3Gb/s) LSI SAS2308 (SAS 6Gb/s)		
RAID Support	RAID 0, 1, 5, 10 (Intel® RSTe 3.0) RAID 0, 1, 1E, 10 (LSI Integrated RAID)		
Networking	(3) GbE (shared IPMI NIC), or (2) 10GbE + (1) GbE (shared IPMI NIC) (-2T SKU)		
PCI Expansion Slots	(4) PCI-E (Gen.3) x16 slots + (2) PCI-E (Gen.3) x8 slots (1) PCI 32/33MHz		
Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B7055F48V8HR	(8) hot-swap 3.5"	(2) 4-port SAS/ SATA 6Gb/s	(2+1) 1,540W RPSU
B7055F48W8HR	(8) hot-swap 3.5"	(2) 4-port SAS/ SATA 6Gb/s	(2+1) 1,540W RPSU
B7055F48V8HR-2T (BTO)	(8) hot-swap 3.5"	(2) 4-port SAS/ SATA 6Gb/s	(2+1) 1,540W RPSU
*B7055F48W8HR-NXXXX	(8) hot-swap 3.5"	(2) 4-port SAS/ SATA 6Gb/s	(2+1) 1,540W RPSU



GA80-B7061

B7061G80W4H (BTO)



80 PLUS PLATINUM
1U Server Platform Designed for up to 2x GPU Cards Deployment



Model Number	GA80-B7061		
Enclosure Form Factor	1U (31.5" in depth)		
Supported CPU	(2) Intel® Xeon® Processor E5-2600 v2 Series (Ivy Bridge-EP)		
Chipset	Intel® C602 PCH		
Chipset Interconnection	Intel® QPI 8.0/ 7.2/ 6.4 GT/s		
Number of DIMM Slot	16/ (8+8)		
Memory Type (max. capacity)	LR-DDR3 1866/1600/1333/ 1066 w/ ECC (512GB) R-DDR3 1866/1600/1333/ 1066 w/ ECC (256GB) U-DDR3 1866/1600/1333/ 1066 w/ ECC (128GB)		
Storage Controller	LSI SAS2308 (SAS 6Gb/s)		
RAID Support	RAID 0, 1, 1E, 10 (LSI Integrated RAID)		
Multimedia Drive	N/A		
Networking	(2) GbE + (1) PHY dedicated IPMI		
PCI Expansion Slots	(2) PCI-E (Gen.3) x16; (1) PCI-E (Gen.3) x8		
Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B7061G80W4H (BTO)	(4) hot-swap 2.5"	4-port SAS/ SATA 6Gb/s	(1) 1,200W PSU

Server Board Workstation Board

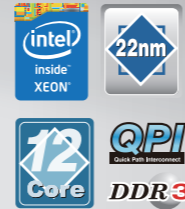


S7045

S7045AG2NR / S7045WGM2NR
S7045GM4NR / S7045WGM4NR (BTO)

- Processor** - Dual LGA1356 sockets support Intel® Xeon® E5-2400 v2 series processors (Ivy Bridge-EN)
- Chipset** - Intel® C602 PCH
- Intel® C602 PCH + TYAN TRK#5 ROM Kit (-W SKU)
- Memory** - (6+6) DDR-III DIMM slots
- Support up to 384GB of LRDIMM 1333/1066 w/ ECC memory
- Support up to 192GB of R-DDR3 1600/1333/1066 w/ ECC memory
- Support up to 96GB of U-DDR3 1333/1066 w/ ECC memory
- Expansion** - (1) PCI-E (Gen.3) x8 slot (#7) - (1) PCI-E (Gen.3) x16 slot (w/ x8 link) (#6)
- (1) PCI-E (Gen.3) x8 slot (w/ x8 link) (#5) - (1) PCI-E (Gen.3) x16 slot (#4)
- (1) PCI-E (Gen.3) x8 slot (w/ x4 link) (#2) - (1) PCI 32/33MHz slot (#1)
- Storage** - (2) SATA 6Gb/s connectors (Intel® RSTe 3.0)
- (4) SATA 3Gb/s connectors (Intel® RSTe 3.0)
- (8) SAS 3Gb/s ports by (8) SATA connectors (Intel® RSTe 3.0) (-W SKU)
- Network** - (2) GbE (via 2x Intel® 82574L) (S7045AG2NR/S7045WGM2NR)
- (4) GbE (via Intel® I350-AM2 + 2x Intel® 82574L) (S7045GM4NR/S7045WGM4NR)
- Video** - ASPEED AST2300 Integrated Graphics
- Audio** - Realtek ALC262 audio CODEC (S7045AG2NR)
- Management** - ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM) (*S7045AG2NR without BMC)
- Form Factor** - SSI EEB (12" x 13", 305mm x 330mm)

Server Board Workstation Board



S7055

S7055AGM3NR / S7055WAGM3NR
S7055WGM3NR / S7055AGM3NR-2T

- Processor** - Dual LGA2011 sockets support Intel® Xeon® E5-2600 v2 series processors (Ivy Bridge-EP)
- Chipset** - Intel® C602 PCH
- Intel® C602 PCH + TYAN TRK#5 ROM Kit (S7055WGM3NR/S7055WAGM3NR)
- Memory** - (4+4) DDR-III DIMM slots
- Support up to 256GB of LRDIMM 1866/1600/1333/1066 w/ ECC memory
- Support up to 128GB of R-DDR3 1866/1600/1333/1066 w/ ECC memory
- Support up to 64GB of U-DDR3 1866/1600/1333/1066 w/ ECC memory
- Expansion** - (4) PCI-E (Gen.3) x16 slots - (2) PCI-E (Gen.3) x8 slots
- (1) PCI 32/33MHz slot
- Storage** - (2) SATA 6Gb/s connectors (Intel® RSTe 3.0)
- (4) SATA 3Gb/s connectors (Intel® RSTe 3.0)
- (8) SAS 3Gb/s ports by (2) mini-SAS connectors (Intel® RSTe 3.0) (S7055WGM3NR/S7055WAGM3NR)
- Network** - (3) GbE (via Intel® I350-BT2 and Intel® 82574L) (S7055AGM3NR/S7055WGM3NR/S7055WAGM3NR)
- (2) 10GbE (via Intel® X540-AT2) + (1) GbE (Intel® 82574L) (S7055AGM3NR-2T)
- Video** - ASPEED AST2300 Integrated Graphics
- Audio** - Realtek ALC262 audio CODEC (S7055AGM3NR/S7055WAGM3NR/S7055AGM3NR-2T)
- Management** - ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM)
- Form Factor** - SSI EEB (12" x 13", 305mm x 330mm)

Server Board Workstation Board

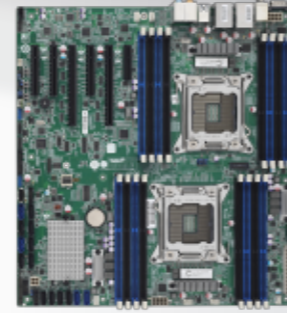


S7050

S7050A2NR / S7050GM2NR / S7050GM4NR / S7050WGM4NR
S7050GP2NR-DLE / S7050G2NR-DLE

- Processor** - Dual LGA2011 sockets support Intel® Xeon® E5-2600 v2 series processors (Ivy Bridge-EP)
- Chipset** - Intel® C602 PCH
- Intel® C602 PCH + TYAN TRK#5 ROM Kit (-W SKU)
- Memory** - (8+8) DDR-III DIMM sockets
- (4+4) DDR-III DIMM slots (-DLE SKU)
- Support up to 512GB of LRDIMM 1866/1600/1333/1066 w/ ECC memory
- Support up to 256GB of R-DDR3 1866/1600/1333/1066 w/ ECC memory
- Support up to 128GB of U-DDR3 1866/1600/1333/1066 w/ ECC memory
- Expansion** - (2) PCI-E (Gen.3) x16 slots (w/ x16 or x8 link)
- (2) PCI-E (Gen.3) x8 slots (w/ x0 or x8 link)
- (1) PCI-E (Gen.3) x4 slot
- (1) PCI 32/33MHz slot
- Storage** - (2) SATA 6Gb/s connectors (Intel® RSTe 3.0)
- (4) SATA 3Gb/s connectors (Intel® RSTe 3.0)
- (8) SATA 3Gb/s connectors (Intel® RSTe 3.0) (w/o -W SKU)
- (8) SAS 3Gb/s ports by (8) SATA connectors (Intel® RSTe 3.0) (-W SKU)
- Network** - (4) GbE (via Intel® I350-AM2 + 2x Intel® 82574L) (S7050GM4NR/S7050WGM4NR)
- (2) GbE (via Intel® 82574L) (S7050GM2NR/S7050A2NR)
- Video** - ASPEED AST2300 Integrated Graphics
- ASPEED AST1300 Integrated Graphics (S7050G2NR-DLE)
- Audio** - Realtek ALC262 audio CODEC (S7050A2NR)
- Management** - ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM) (*S7050A2NR with BMC)
- ASPEED AST2300 (IPMI v2.0 compliant) (S7050GP2NR-DLE)
- Form Factor** - SSI EEB (12" x 13", 305mm x 330mm)

Server Board Workstation Board



S7065

S7065A2NRF / S7065WA2NRF

- Processor** - Dual LGA2011 sockets support Intel® Xeon® E5-2600 v2 series processors (Ivy Bridge-EP)
- Chipset** - Intel® C602 PCH
- Intel® C602 PCH + TYAN TRK#5 ROM Kit (-W SKU)
- Memory** - (8+8) DDR-III DIMM sockets
- Support up to 512GB of LRDIMM 1866/1600/1333/1066 w/ ECC memory
- Support up to 256GB of R-DDR3 1866/1600/1333/1066 w/ ECC memory
- Support up to 128GB of U-DDR3 1866/1600/1333/1066 w/ ECC memory
*Speed 1866 only for 1 slot per channel 1.5V(Blue color DIMM slot)
- Expansion** - (1) PCI-E (Gen.3) x4 slot (#6)
- (2) PCI-E (Gen.3) x16 slots (w/ x16 or x8 link) (#5, #3)
- (2) PCI-E (Gen.3) x8 slots (w/ x0 or x8 link) (#4, #2)
- (1) PCI-E (Gen.2) x8 slot (w/ x4 link) (#1)
- Storage** - (2) SATA 6Gb/s connectors (Intel® RSTe 3.0)
- (4) SATA 3Gb/s connectors (Intel® RSTe 3.0)
- (8) SAS 3Gb/s ports by (8) SATA connectors (Intel® RSTe 3.0) (-WSKU)
- Network** - (2) GbE (via Intel® 82574L)
- Audio** - Realtek ALC892 7.1 Channel HD Audio Codec with Content Protection
- Form Factor** - SSI EEB (12" x 13", 305mm x 330mm)

GPU

GPU

TYAN INTEL-BASED CLOUD PLATFORMS



TYAN offers a full array of products that provide web-based hardware to meet users' business needs toward cloud computing with lower cost. TYAN's Intel® Xeon® Processor E5-2600/ E5-2600 V2/ E3-1200 Product Families based platforms or Intel® Xeon® 5600 Series Processor supporting platforms offer reliability, scalability, flexibility, high density, and remote management capability that deliver higher computing performance with lower cost. TYAN's broad product portfolio provides users with multiple hardware solutions that meet the needs of public, private, and hybrid cloud infrastructure.

- Target Applications:**
- Cloud Service Providers that Offer Infrastructure as a Service (IaaS), Platform as a Service (PaaS), and Software as a Service (SaaS)
 - E-Commerce and Web-based Mail services
 - Online Real Time Streaming Services such as Consulting or Training
 - Back-end Office or Remote Office
 - Functional Verticals, VARs, or SI that Assist to Deploy Cloud Computing Hardware Environments for Enterprises or SMBs

FM65-B5531

B5531F65X18-160PV2R
B5531F65X18-160PV2R-HE



CLOUD



4U High-Density and Power-Efficient Platform for VHD/VDI Applications



Model Number	FM65-B5531			
Enclosure Form Factor	4U (25.6" in depth) / 18 Nodes			
Supported CPU (per node)	(1) Intel® Xeon® E3-1285L v3 (Haswell-DT)			
Chipset (per node)	Intel® C222 PCH Intel® C226 PCH (-HE SKU)			
Number of DIMM Slot (per node)	4			
Memory Type (max. capacity) (per node)	U-DDR3 VLP DIMM 1600/1333/1066 w/ ECC (32GB)			
Storage Controller (per node)	Intel® C222 PCH (SATA 6Gb/s) Intel® C226 PCH (SATA 6Gb/s)			
RAID Support (per node)	RAID 0, 1, 5, 10 (Intel® RST 3.x) (3) GbE (shared IPMI NIC)			
Networking (per node)	(2) GbE (shared IPMI NIC)(-HE SKU)			
	Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
	B5531F65X18-160PV2R	(2) Internal 2.5" (per node)	N/A	(2+1) 1600W RPSU
	B5531F65X18-160PV2R-HE	(2) Internal 2.5" (per node)	N/A	(2+1) 1600W RPSU

GT24-B7067

B7067G24V4H-2T / B7067G24W4H-2T



CLOUD



1U Rack-Optimized Server Platform for CLOUD



Model Number	GT24-B7067			
Enclosure Form Factor	1U (25.4" in depth)			
Supported CPU	(2) Intel® Xeon® E5-2600 v2 Series (Ivy Bridge-EP)			
Chipset	Intel® C602 PCH			
QuickPath Interconnect	Intel® QPI 8.0/ 7.2/ 6.4GT/s			
Number of DIMM Slot	16/(8+8)			
Memory Type (max. capacity)	LR-DDR3 1866/1600/1333/ 1066 w/ ECC (512GB) R-DDR3 1866/1600/ 1333/ 1066 w/ ECC (256GB) U-DDR3 1866/1600/1333/ 1066 w/ ECC (128GB)			
Storage Controller	Intel® C602 PCH (SATA 6Gb/s & 3Gb/s) LSI SAS2308 (SAS 6Gb/s)			
RAID Support	RAID 0, 1, 5, 10 (Intel® RSTe 3.0) RAID 0, 1, 1E, 10 (LSI Integrated RAID)			
Networking	(2) 10GbE SFP+ + (1) GbE (shared with IPMI)			
PCI Expansion Slots	(1) PCI-E (Gen.3) x16 (w/ x8 link)			
	Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
	B7067G24V4H-2T	(4) hot-swap 3.5"/2.5"	4-port SAS/ SATA 6Gb/s	(1) 500W PSU
	B7067G24W4H-2T	(4) hot-swap 3.5"/2.5"	4-port SAS/ SATA 6Gb/s	(1) 500W PSU

YR292-B5518-X4

B7058Y190X2-045GV4H



CLOUD



2U High-Density and Power-Efficient Server Platform for Data Centers



Model Number	YR292-B5518-X4			
Enclosure Form Factor	2U (28.74" in depth) / 4 Nodes			
Supported CPU (per node)	(1) Intel® Xeon® E3-1200 v2 Series (Ivy Bridge-DT)			
Chipset (per node)	Intel® C204 PCH			
Number of DIMM Slot (per node)	4			
Memory Type (max. capacity)(per node)	U-DDR3 1600/1333/1066 w/ ECC (32GB)			
Storage Controller (per node)	Intel® C204 PCH (SATA 6Gb/s & 3Gb/s)			
RAID Support (per node)	RAID 0, 1, 5, 10 (Intel® RST 11.x)			
Networking (per node)	(2) GbE + (1) IPMI			
PCI Expansion Slots (per node)	(1) PCI-E (Gen.3) x16			
	Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
	B5518Y292X4-080V4HR	(4) Hot-swap 2.5" (per node)	4-port SAS/ SATA 6Gb/s (per node)	(1+1) 800W RPSU

GT62A-B5512

B7058Y190X2-045GV4H



CLOUD



1U Rack-Optimized Server Platform for CLOUD



Model Number	GT62A-B5512			
Enclosure Form Factor	1U (25.4" in depth)			
Supported CPU	(1) Intel® Xeon® E3-1200 v2 series (Ivy Bridge-DT)			
Chipset	Intel® C204 PCH			
Number of DIMM Slot	4			
Memory Type (max. capacity)	U-DDR3 1600/1333/1066 w/ ECC (32GB)			
Storage Controller	Intel® C602 PCH (SATA 6Gb/s & 3Gb/s) LSI SAS2008 (SAS 6Gb/s)			
RAID Support	RAID 0, 1, 5, 10 (Intel® RST 11.x) RAID 0, 1, 10 (LSI Integrated RAID)			
Networking	(2) GbE + (1) PHY dedicated IPMI			
PCI Expansion Slots	(1) PCI-E (Gen.3) x8			
	Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
	B5512G62AW10H	(10) hot-swap 2.5"	10-port SAS/ SATA 6Gb/s	(1) 500W PSU
	B5512G62AV10H	(10) hot-swap 2.5"	10-port SAS/ SATA 6Gb/s	(1) 500W PSU

*Need a discrete HBA to enable all ten (10) drives



A Broad Portfolio of Enclosures Compatible with Multiple Motherboards Fitting in Different Environments Ranging from Embedded, SMB, Cloud computing, GPU to HPC.

TYAN presents a wide range of enclosures compatible with various server and workstation motherboards that offer outstanding reliability, flexibility and scalability in a cost-effective package. These server enclosures present an outstanding value for system integrators, OEM/ODM manufacturers, and channel partners alike. The latest array of TYAN chassis kits are available in 1U, 2U or 4U form factors and support extensive motherboard product lines. TYAN's wide range of chassis kits combine customer requirements of affordable total cost of ownership with massive computing power.

CGN70
KGN70M1-077GV8HRFE



2U Rackmount Chassis With 8x 3.5" Hot-swap HDD Bays

Model Number	KGN70A		
Enclosure Form Factor	2U (27.56" in depth)		
Supported MB size	SSI EEB/ EATX/ SSI CEB		
Storage	(8) 3.5" hot-swap SAS/SATA HDDs		
Cooling FANS	(4) hot-swap 6038 fans (Default)		
PCI Expansion Slots	(6) half-height slots (M1 SKU), or (1+1) ERP1U 770W RPSU, 80+ Gold		
System Power	(1+1) ERP1U 770W RPSU, 80+ Gold		
Standard Model	Number of HDD Bays	Storage Backplane	Power Supplies
KGN70M1-077GV8HRFE	(8) hot-swap 3.5"	(1) 8-port SAS/SATA 6Gb/s	(1+1) 770W RPSU

KTN70
KTN70M1-077GV12HRFE



2U Rackmount Chassis With 12x 3.5" Hot-swap HDD Bays

Model Number	KTN70		
Enclosure Form Factor	2U (27.56" in depth)		
Supported MB size	SSI EEB/ SSI CEB		
Storage	(12) 3.5" hot-swap SAS/SATA 6Gb/s HDDs and (2) 2.5" internal SAS/SATA HDDs		
Cooling FANS	(4) hot-swap 6038 fans		
PCI Expansion Slots	(6) half-height slots (M1 SKU)		
System Power	(1+1) ERP1U 770W hot-swap RPSU 80+ Gold		
Standard Model	Number of HDD Bays	Storage Backplane	Power Supplies
KTN70M1-077GV12HRFE	(12) hot-swap 3.5"+ (2) internal 2.5"	(1) 12-port SAS/SATA 6Gb/s	(1+1) 770W RPSU

KYM70
KYM70M1-080PV36HRFC



4U Rackmount Chassis With 36x 3.5" Hot-swap HDD Bays

Model Number	KYM70		
Enclosure Form Factor	4U (27.56" in depth)		
Supported MB size	SSI EEB/ SSI CEB		
Storage	(36) 3.5" hot-swap SAS/SATA HDDs		
Cooling FANS	(5+1) hot-swap 12038 fans		
PCI Expansion Slots	(6) half-height slots		
System Power	(1+1) ERP1U 800W RPSU, 80+ Platinum		
Standard Model	Number of HDD Bays	Storage Backplane	Power Supplies
KYM70M1-080PV36HRFC	(36) hot-swap 3.5"	(3) 12-port SAS/SATA 6Gb/s	(1+1) 800W RPSU

KGT62A
KGT62AM2-045SV10HRF6 / KGT62AM2-050GV10HF6
KGT62AM1-045SV10HRF3 / KGT62AM1-050GV10HF3



Mainstream 1U rackmount chassis supports both single & rackmount PSU in various segments

Model Number	KGT62A		
Enclosure Form Factor	1U (24.6" in depth)		
Cooling FANS	Max. (6) 4056 Fans (System dependent)		
Storage	(10) 2.5" Hot-swap SAS/SATA HDDs (Opt.) (1) Slim-type ODD		
PCI Expansion Slots	Max. (2) FH/HL PCI-E slot via riser		
Power Supply	(1)EPS1U single power supply (1+1)ERP1U hot-swap redundant power supply		
Support MB size	SSI EEB/ EATX (12"x13"), SSI CEB (12" x 10.5"), ATX (12" x 9.6")		
Dimension of Chassis	H x W x D (inch): 1.72" x 17.2" x 24.6"		
Standard Model	Number of HDD Bays	Storage Backplane	Power Supplies
KGT62AM2-045SV10HRF6	(10) hot-swap 2.5"	(2) Full-Height	(1+1) 450W 80+ Silver
KGT62AM2-050GV10HF6	(10) hot-swap 2.5"	(2) Full-Height	(1) 500W 80+ Gold
KGT62AM1-045SV10HRF3	(10) hot-swap 2.5"	(1) Full-Height	(1+1) 450W 80+ Silver
KGT62AM1-050GV10HF3	(10) hot-swap 2.5"	(1) Full-Height	(1) 500W 80+ Gold

CGN70A
KGN70AM1-077GV18HRFE



2U Rackmount Chassis With 18x 2.5" Hot-swap HDD Bays

Model Number	KGN70A		
Enclosure Form Factor	2U (27.56" in depth)		
Supported MB size	SSI EEB/ SSI CEB		
Storage	(18) 2.5" hot-swap SAS/SATA HDDs		
Cooling FANS	(4) hot-swap 6038 fans (Default)		
PCI Expansion Slots	(6) half-height slots (M1 SKU), or (1+1) ERP1U 770W RPSU, 80+ Gold		
System Power	(1+1) ERP1U 770W RPSU, 80+ Gold		
Standard Model	Number of HDD Bays	Storage Backplane	Power Supplies
KGN70AM1-077GV18HRFE	(18) hot-swap 2.5"	(2) 8-port + (1) 2-port SAS/SATA 6Gb/s	(1+1) 770W RPSU

KTN70A
KTN70AM1-077GV24HRFE



2U Rackmount Chassis With 24x 2.5" Hot-swap HDD and 2x 2.5" Internal HDD Bays

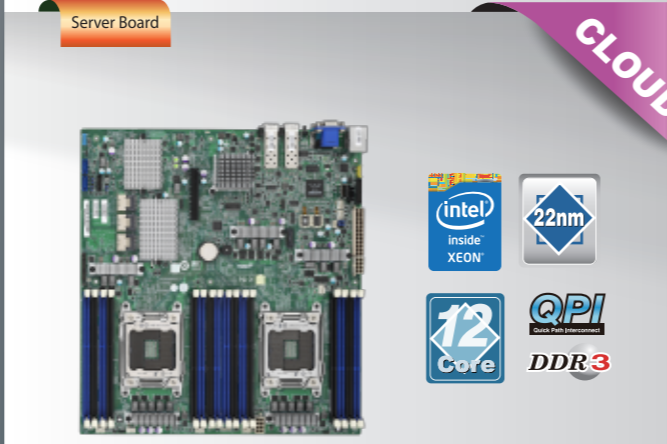
Model Number	KTN70A		
Enclosure Form Factor	2U (27.56" in depth)		
Supported MB size	SSI EEB/ SSI CEB		
Storage	(24) 2.5" hot-swap SAS/SATA HDDs + (2) 2.5" Internal HDD Bays		
Cooling FANS	(4) hot-swap 6038 fans (Default)		
PCI Expansion Slots	(6) half-height slots (M1 SKU), or (1+1) ERP1U 770W RPSU, 80+ Gold		
System Power	(1+1) ERP1U 770W RPSU, 80+ Gold		
Standard Model	Number of HDD Bays	Storage Backplane	Power Supplies
KTN70AM1-077GV24HRFE	(24) hot-swap 2.5" + (2) internal 2.5"	(3) 8-port SAS/SATA 6Gb/s	(1+1) 770W RPSU



S7063

S7063WGM3NR-2T / S7063GM3NR-2T

- Processor** - Dual LGA2011 sockets support Intel® Xeon® E5-2600 v2 series processors (Ivy Bridge-EP)
- Chipset** - Intel® C602 PCH
- Memory** - (8+8) DDR-III DIMM slots
- Support up to 512GB of LRDIMM 1866/1600/1333/1066 w/ ECC memory
- Support up to 256GB of R-DDR3 1866/1600/1333/1066 w/ ECC memory
- Support up to 128GB of U-DDR3 1866/1600/1333/1066 w/ ECC memory
- Expansion** - (1) PCI-E (Gen.3) x8 slots
- Storage** - (2) SATA 6Gb/s connectors (Intel® RSTe 3.0)
- (4) SATA 3Gb/s ports by (1) mini-SAS connector (Intel® RSTe 3.0)
- (8) SAS 6Gb/s ports by (2) mini-SAS connectors (LSI RAID stack) (-W SKU)
- Network** - (2) 10GbE SFP+ (via Intel® 82599ES)
- (1) GbE shared IPMI (via Intel® 82574L)
- Video** - ASPEED AST2300 Integrated Graphics
- Management** - ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM)
- Form Factor** - EATX (12" x 13", 305mm x 330mm)



S7067

S7067WGM3NR-2T / S7067GM3NR-2T

- Processor** - Dual LGA2011 sockets support Intel® Xeon® E5-2600 v2 series processors (Ivy Bridge-EP)
- Chipset** - Intel® C602 PCH
- Memory** - (8+8) DDR-III DIMM slots
- Support up to 512GB of LRDIMM 1866/1600/1333/1066 w/ ECC memory
- Support up to 256GB of R-DDR3 1866/1600/1333/1066 w/ ECC memory
- Support up to 128GB of U-DDR3 1866/1600/1333/1066 w/ ECC memory
- Expansion** - (1) PCI-E (Gen.3) x8 slots
- Storage** - (2) SATA 6Gb/s connectors (Intel® RSTe 3.0)
- (4) SATA 3Gb/s ports by (1) mini-SAS connector (Intel® RSTe 3.0)
- (8) SAS 6Gb/s ports by (2) mini-SAS connectors (LSI RAID stack) (-W SKU)
- Network** - (2) 10GbE SFP+ (via Broadcom® BCM57810S)
- (1) GbE shared IPMI (via Intel® 82574L)
- Video** - ASPEED AST2300 Integrated Graphics
- Management** - ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM)
- Form Factor** - EATX (12" x 13", 305mm x 330mm)



S5512

S5512G2NR-LE / S5512WGM2NR / S5512GM4NR

- Processor** - Single LGA1155 socket supports Intel® Xeon® E3-1200/ E3-1200 v2 series processors (Ivy Bridge-DT)
- Chipset** - Intel® C202 PCH (S5512G2NR-LE)
- Intel® C204 PCH (S5512GM4NR)
- Intel® C204 PCH + LSI SAS2008 (-W SKU)
- Memory** - (4) DDR-III DIMM slots
- Support up to 32GB of U-DDR3 1600/1333/1066 w/ ECC memory
- Expansion** - (1) PCI-E (Gen.2/Gen.3) x16 slot (w/ x8 link)
- (1) PCI-E (Gen.2/Gen.3) x8 slot (w/ x8 link)
- (1) PCI-E (Gen.2/Gen.3) x8 slot (w/ x4 link) (S5512GM4NR)
- (2) PCI-E (Gen.2) x1 slots
- (1) PCI 32/33MHz slot
- Storage** - (2) SATA 6Gb/s connectors (Intel® RST 11.x)
- (4) SATA 3Gb/s connectors (Intel® RST 11.x)
- (8) SAS 6Gb/s connectors (LSI RAID stack) (-W SKU)
- Network** - (2) GbE (via 2x Intel® 82574L) (S5512G2NR-LE/S5512WGM2NR)
- (4) GbE (via 4x Intel® 82574L) (S5512GM4NR)
- Video** - ASPEED AST2150 Integrated Graphics
- Management** - ASPEED AST2150 (IPMI v2.0 compliant w/ iKVM) (*S5512G2NR-LE without BMC)
- Form Factor** - ATX (12" x 9.6", 305mm x 243.84mm)



S5530

S5530WGM5NR-LE-2T

- Processor** - Single LGA1150 socket supports Intel® Xeon® E3-1200 v3/ 4th generation Intel® Core™ i3 series processors (Haswell-DT)
- Chipset** - Intel® C222 PCH
- Memory** - (4) DDR-III DIMM slots
- Support up to 32GB U-DDR3 1600/1333 w/ ECC
- Expansion** - (1) PCI-E (Gen.2) x4 slot
- Storage** - (2) SATA 6Gb/s connectors (Intel® RSTe 3.6)
- (4) SATA 3Gb/s connectors (Intel® RSTe 3.6)
- (8) SAS 6Gb/s by (2) Mini-SAS connectors (LSI RAID stack)
- Network** - (2) GbE (via 2x Intel® i210)
- (2) 10GbE SFP+ (via Broadcom® BCM57810S)
- (1) GbE shared IPMI NIC (via Intel® i217)
- Video** - ASPEED AST2300 Integrated Graphics
- Management** - ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM)
- Form Factor** - ATX (12" x 9.6", 305mm x 243.84mm)

TYAN

INTEL-BASED SMB PLATFORMS



Multiple TYAN® platforms offer small and medium sized businesses (SMB) the capability to access and execute a greater amount of computer applications by sharing resources in an effective and efficient way. Supporting the Intel® Xeon® Processor E5-2600-V2/ E5-2400/ E3-1200 product families and Intel Xeon 5600 Series Processor, TYAN's SMB platforms allow customers to manage multiple workloads with higher computing performance at lower total cost of ownership. These platforms feature reliable, affordable, and simple setup. They also offer easy management and support industry standard operating systems that make them the ideal hardware solution for the small and remote office, entry-level server applications, and the standard rackmount server room.

- Target Applications:**
- Entry-level Server and General Server Room
 - Computer Services
 - Automotive and Industrial Products
 - Consumer Products
 - Education
 - Electronics
 - Energy & Utilities
 - Fabrication & Assembly
 - Banking, Insurance and Financial Markets
 - Government
 - Healthcare
 - Media & Entertainment
 - E-commerce and Retail
 - Web hosting and Database
 - Telecommunications

HPC/GPU Platforms

Cloud Platforms

SMB Platforms

Embedded Platforms

HPC/GPU Platforms

Cloud Platforms

SMB Platforms

Embedded Platforms

GT20A-B7040

B7040G20AV4H



SMB

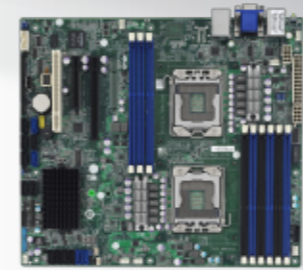
80 PLUS GOLD
1U Rack-Optimized Cost-Effective Platform



Model Number	GT20A-B7040		
Enclosure Form Factor	1U (22.4" in depth)		
Supported CPU	(2) Intel® Xeon® E5-2400 v2 Series (Ivy Bridge-EN)		
Chipset	Intel® C602 PCH		
QuickPath Interconnect	Intel® QPI 8.0/ 7.2/ 6.4GT/s		
Number of DIMM Slot	9/ (6+3)		
Memory Type (max. capacity)	LR-DDR3 1333/ 1066 w/ ECC (288GB) R-DDR3 1600/ 1333/ 1066 w/ ECC (144GB) U-DDR3 1333/ 1066 w/ ECC (72GB)		
Storage Controller	Intel® C602 PCH (SATA 6Gb/s & 3Gb/s)		
RAID Support	RAID 0, 1, 5, 10 (Intel® RSTe 3.0)		
Networking	(2) GbE (shared IPMI NIC)		
PCI Expansion Slots	(1) PCI-E (Gen.3) x8		
Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B7040G20AV4H	(4) hot-swap 3.5"/2.5"	4-port SAS/ SATA 6Gb/s	(1) 500W PSU

Server Board

SMB



S7040

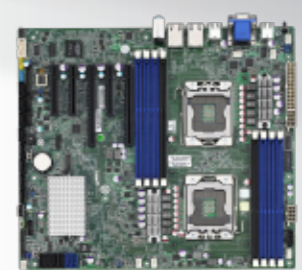
S7040G2NR / S7040GM2NR / S7040WGM2NR / S7040GM4NR

Processor	• Dual LGA1356 sockets support Intel® Xeon® E5-2400 v2 series processors (Ivy Bridge-EN)
Chipset	• Intel® C602 PCH • Intel® C602 PCH + TYAN TRK#5 ROM Kit (-W SKU)
Memory	• (6+3) DDR-III DIMM sockets • Support up to 288GB of LRDIMM 1333/1066 w/ ECC memory • Support up to 144GB of R-DDR3 1600/1333/1066 w/ ECC memory • Support up to 72GB of U-DDR3 1333/1066 w/ ECC memory
Expansion	• (1) PCI-E (Gen.3) x16 slot (w/ x8 link) • (1) PCI-E (Gen.3) x8 slot (w/ x4 link) • (1) PCI-E (Gen.3) x8 slot (w/ x4 link) • (1) PCI 32/33MHz slot
Storage	• (2) SATA 6Gb/s connectors (Intel® RSTe 3.0) • (4) SATA 3Gb/s connectors (Intel® RSTe 3.0) • (8) SAS 3Gb/s connectors (Intel® RSTe 3.0) (-W SKU)
Network	• (2) GbE (via Intel® I350-AM2) • (4) GbE (via Intel® I350-AM2 and 2x Intel® 82574L) (S7040GM4NR)
Video	• ASPEED AST2300 Integrated Graphics • ASPEED AST1300 Integrated Graphics (S7040G2NR)
Management	• ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• SSI CEB (12" x 10.6", 305mm x 269.24mm)

Server Board

Workstation Board

SMB



S7042

S7042WAGM2NR / S7042AGM2NR
S7042GP2NR-B / S7042G2NR-LE-B

Processor	• Dual LGA1356 sockets support Intel® Xeon® E5-2400 v2 series processors (Ivy Bridge-EN)
Chipset	• Intel® C602 PCH • Intel® C602 PCH + TYAN TRK#5 ROM Kit (-W SKU)
Memory	• (4+4) DDR-III DIMM slots • Support up to 288GB of LRDIMM 1333/1066 w/ ECC memory • Support up to 144GB of R-DDR3 1600/1333/1066 w/ ECC memory • Support up to 72GB of U-DDR3 1333/1066 w/ ECC memory
Expansion	• (2) PCI-E (Gen.3) x16 slot • (1) PCI-E (Gen.3) x8 slot • (2) PCI-E (Gen.3) x8 slot (w/ x4 link)
Storage	• (2) SATA 6Gb/s connectors (Intel® RSTe 3.0) • (8) SATA 3Gb/s connectors (Intel® RSTe 3.0) (S7042AGM2NR) • (8) SAS 3Gb/s connectors (Intel® RSTe 3.0) (-W SKU)
Network	• (2) GbE (via 2x Intel® i210 and shared IPMI NIC)
Video	• ASPEED AST2300 Integrated Graphics • ASPEED AST1300 Integrated Graphics (S7042G2NR-LE-B) • Realtek ALC262 Integrated Graphics
Management	• ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM) • ASPEED AST2300 (IPMI v2.0 compliant) (S7042GP2NR-B)
Form Factor	• SSI CEB (12" x 10.5", 305mm x 267mm)

GT24-B7066

B7066G24V4H / B7066G24W4HR(BTO) / B7066G24W4H



SMB

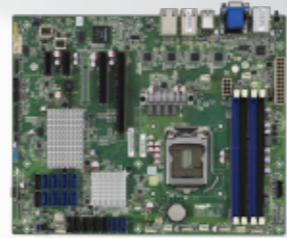
80 PLUS GOLD
1U Rack-Optimized Server Platform for HPC



Model Number	GT24-B7066		
Enclosure Form Factor	1U (25.4" in depth)		
Supported CPU	(2) Intel® Xeon® E5-2600 v2 Series (Ivy Bridge-EP)		
Chipset	Intel® C602 PCH		
QuickPath Interconnect	Intel® QPI 8.0/ 7.2/ 6.4GT/s		
Number of DIMM Slot	16/(8+8)		
Memory Type (max. capacity)	LR-DDR3 1866/1600/1333/ 1066 w/ ECC (512GB) R-DDR3 1866/1600/ 1333/ 1066 w/ ECC (256GB) U-DDR3 1866/1600/1333/ 1066 w/ ECC (128GB)		
Storage Controller	Intel® C602 PCH (SATA 6Gb/s & 3Gb/s) LSI SAS2308 (SAS 6Gb/s)		
RAID Support	RAID 0, 1, 5, 10 (Intel® RSTe 3.0) RAID 0, 1, 1E, 10 (LSI Integrated RAID)		
Networking	(3) GbE (shared IPMI NIC)		
PCI Expansion Slots	(2) PCI-E (Gen.3) x16		
Standard Model	Number of HDD Bay	Storage Backplane	Power Supply
B7066G24V4H	(4) hot-swap 3.5"/2.5"	4-port SAS/ SATA 6Gb/s	(1) 500W EPS1U
B7066G24W4HR(BTO)	(4) hot-swap 3.5"/2.5"	4-port SAS/ SATA 6Gb/s	(1+1) 450W RPSU
B7066G24W4H	(4) hot-swap 3.5"/2.5"	4-port SAS/ SATA 6Gb/s	(1) 500W PSU

Server Board

SMB



S5532

S5532GM2NR-LE / S5532WGM2NR-LE / S5532GM4NR-LE
S5532G2NR-LE / S5532WGM4NR-LE

Processor	• Single LGA1150 socket supports Intel® Xeon® E3-1200 v3/ 4th generation Intel® Core™ i3 series processors (Haswell-DT)
Chipset	• Intel® C222 PCH
Memory	• (4) DDR-III DIMM slots • Support up to 32GB U-DDR3 1600/1333 w/ ECC
Expansion	• (1) PCI-E (Gen.3) x16 slot (w/ x8 link) • (1) PCI-E (Gen.3) x8 slot (N/A on -W SKU) • (1) PCI-E (Gen.2) x8 slot (w/ x1 link) • (2) PCI-E (Gen.2) x4 slots (w/ x1 link)
Storage	• (2) SATA 6Gb/s connectors (Intel® RSTe 3.6) • (4) SATA 3Gb/s connectors (Intel® RSTe 3.6) • (8) SAS 6Gb/s connectors (LSI RAID stack) (-W SKU)
Network	• (4) GbE (via 4x Intel® i210) (-4NR SKU) • (2) GbE (via 2x Intel® i210) (-2NR SKU) • (1) FE dedicated IPMI (via Broadcom® BCM5221A) (-M SKU)
Video	• ASPEED AST2300 Integrated Graphics
Management	• ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• ATX (12" x 9.6", 305mm x 243.84mm)

Server Board

SMB



S5533

S5533GM2NR-LE

Processor	• Single LGA1150 socket supports Intel® Xeon® E3-1200 v3/ 4th generation Intel® Core™ i3 series processors (Haswell-DT)
Chipset	• Intel® C222 PCH
Memory	• (2) DDR-III DIMM slots • Support up to 16GB U-DDR3 1600/1333 w/ ECC
Expansion	• (1) PCI-E (Gen.3) x16 slot
Storage	• (2) SATA 6Gb/s connectors (Intel® RSTe 3.6) • (4) SATA 3Gb/s connectors (Intel® RSTe 3.6)
Network	• (2) GbE (via 2x Intel® i210) • (1) FE dedicated IPMI (via Realtek® RTL 8211EL)
Video	• ASPEED AST2300 Integrated Graphics
Management	• ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• Mini-ITX (6.7" x 6.7", 170mm x 170mm)

TYAN

INTEL-BASED EMBEDDED PLATFORMS



Many of TYAN's Intel based platforms are designed for embedded applications which ensure that customers will have strong performance, consistent reliability, and low cost in small form factor. These TYAN products are ideal platforms for customers with critical requirements from telecom, networking, storage, medical imaging, embedded servers, security and surveillance appliances.

Target Applications:

- Telecommunications
- Networking
- Security & Surveillance
- Digital Signage and Imaging
- Set Top Box
- Gaming
- Storage
- Medical & Healthcare



S5535

S5535AG2NR

Processor	• Single LGA1150 socket supports Intel® Core™ i3/i5/i7 series processors (Haswell-DT)
Chipset	• Intel® Q87 PCH
Memory	• (4) DDR-III DIMM slots • Support up to 32GB U-DDR3 1600/1333 Non-ECC
Expansion	• (1) PCI-E (Gen.3) x16 slot • (1) PCI-E (Gen.2) x8 slot (w/ x4 link) • (1) PCI-E (Gen.2) x1 slot
Storage	• (5) SATA 6Gb/s connectors (Intel® RST 12.x)
Network	• (2) GbE (via Intel® i210 & Intel® i217)
Video	• Intel Processor Graphics (pGFX) • Realtek ALC892GR Integrated Graphics
Form Factor	• mATX (9.6" x 9.6", 243.84mm x 243.84mm)



S5532-HE

S5532G2NR-HE

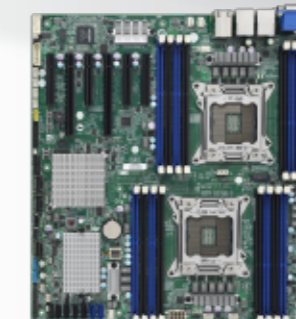
Processor	• Single LGA1150 socket supports Intel® Xeon® E3-1200 v3/ 4th generation Intel® Core™ i3 series processors (Haswell-DT)
Chipset	• Intel® C226 PCH
Memory	• (4) DDR-III DIMM slots • Support up to 32GB U-DDR3 1600/1333 w/ ECC
Expansion	• (1) PCI-E (Gen.3) x16 slot (w/ x8 link) • (1) PCI-E (Gen.3) x8 slot • (1) PCI-E (Gen.2) x8 slot (w/ x1 link) • (2) PCI-E (Gen.2) x4 slots (w/ x1 link)
Storage	• (6) SATA 6Gb/s connectors (Intel® RSTe 3.6)
Network	• (2) GbE (via 2x Intel® i210)
Video	• ASPEED AST1300 Integrated Graphics
Form Factor	• ATX (12" x 9.6", 305mm x 243.84mm)



S5535-HE

S5535AG2NR-HE

Processor	• Single LGA1150 socket supports Intel® Xeon® E3-1200 v3/ 4th generation Intel® Core™ i3 series processors (Haswell-DT)
Chipset	• Intel® C226 PCH
Memory	• (4) DDR-III DIMM slots • Support up to 32GB U-DDR3 1600/1333 w/ ECC
Expansion	• (1) PCI-E (Gen.3) x16 slot • (1) PCI-E (Gen.2) x8 slot (w/ x4 link) • (1) PCI-E (Gen.2) x1 slot*
Storage	• (5) SATA 6Gb/s connectors (Intel® RST 12.x)
Network	• (2) GbE (via Intel® i210 & Intel® i217)
Video	• Intel Processor Graphics (pGFX) • Realtek ALC892GR Integrated Graphics
Form Factor	• mATX (9.6" x 9.6", 243.84mm x 243.84mm)



S7053-HE

S7053GM2NR-HE

Processor	• Dual LGA2011 sockets support Intel® Xeon® E5-2600 v2 series processors (Ivy Bridge-EP)
Chipset	• Intel® C602-J PCH
Memory	• (8+8) DDR-III DIMM sockets • Support up to 512GB of LRDIMM 1866/1600/1333/1066 w/ ECC memory • Support up to 256GB of R-DDR3 1866/1600/1333/1066 w/ ECC memory • Support up to 128GB of U-DDR3 1866/1600/1333/1066 w/ ECC memory
Expansion	• (2) PCI-E (Gen.3) x16 slots • (4) PCI-E (Gen.3) x8 slots
Storage	• (2) SATA 6Gb/s connectors (Intel® RSTe 3.0) • (4) SATA 3Gb/s connectors (Intel® RSTe 3.0)
Network	• (2) GbE (via Intel® I350-AM2)
Video	• ASPEED AST2300 Integrated Graphics
Management	• ASPEED AST2300 (IPMI v2.0 compliant w/ iKVM)
Form Factor	• SSI EEB (12" x 13", 305mm x 330mm)